In the Claims:

- 1 1. (original) A light emitting device of a II-VI group
 compound semiconductor formed on a compound semiconductor
 substrate and having an active layer between an n-type
 cladding layer and a p-type cladding layer, comprising
- a semiconductor barrier layer having a band gap larger than a band gap of said p-type cladding layer, provided between said active layer and said p-type cladding layer.
- 1 2. (original) The semiconductor light emitting device 2 according to claim 1, wherein
- said light emitting device of the II-VI group compound is a ZnSe based light emitting device;
- said n-type cladding layer is an n-type $Zn_{1-x}Mg_xS_ySe_{1-y}$
- 6 (0 < x < 1, 0 < y < 1) layer; and
- said p-type cladding layer is a p-type $Zn_{1-x}Mg_xS_ySe_{1-y}$ (0 < x < 1, 0 < y < 1) layer.
- 3. (original) The semiconductor light emitting device
 according to claim 1, wherein
- magnitude of the band gap of said barrier layer is
 larger by 0.025 eV to 0.5 eV than the band gap of said
 p-type cladding layer.

- 1 4. (currently amended) The semiconductor light emitting device according to claim 1, wherein
- in the band gap of said barrier layer, energy of valence band is approximately the same as or higher than that of said p-type cladding layer, and energy of conductive band is larger than that of said p-type cladding
- 7 layer.
- f. (original) The semiconductor light emitting device
 according to claim 1, wherein
- said barrier layer is of a II-VI group compound semiconductor containing Be.
- 6. (original) The semiconductor light emitting device according to claim 5, wherein
- said barrier layer is of $Zn_{1-x-y}Mg_xBe_ySe$ (0 \leq x + y \leq 1, 0 < x, 0 < y).
- 7. (original) The semiconductor light emitting device according to claim 1, wherein
- said barrier layer is of Zn_{1-x}Mg_xS_vSe_{1-v}.
- 8. (original) The semiconductor light emitting device according to claim 1, comprising
- a semiconductor trap layer having a band gap smaller
 than a band gap of said p-type cladding layer, provided
 between said barrier layer and said p-type cladding layer.

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- 9. (original) The semiconductor light emitting device according to claim 8, having a multi-stacked structure in which a plurality of double-layer-structure of said barrier layer and said trap layer are stacked.
- 1 10. (original) The semiconductor light emitting device according to claim 8, wherein
- said trap layer is of ZnS_xSe_{1-x} (0 $\leq x \leq 0.1$).
- 1 11. (original) The semiconductor light emitting device
 2 according to claim 1, wherein
- said p-type cladding layer is formed of $(Zn_{1-x}Cd_xS)_{1-z}(MgS_{1-y}Se_y)_z \text{ (where } x,\ y,\ z \text{ satisfy } 0 < x \le 1, \\ 0 \le y \le 1,\ 0 \le z < 1).$
- 1 12. (original) The semiconductor light emitting device according to claim 1, wherein
- thickness of said barrier layer is at least 5 nm and at most thickness of said active layer.
- 1 13. (original) The semiconductor light emitting device
 2 according to claim 1, wherein
- an n-type ZnSe single crystal substrate is used as said compound semiconductor substrate.

- 1 14. (original) The semiconductor light emitting device according to claim 1, wherein
- an n-type GaAs single crystal substrate is used as said compound semiconductor substrate.
- 1 15. (original) The semiconductor light emitting device according to claim 1, wherein

in a stacked structure including said compound
semiconductor substrate constituting said ZnSe based light
emitting device, deviation between a peak of X-ray
diffraction of a plane orientation used as an index of
distortion from said substrate and a peak of X-ray
diffraction of said plane orientation from said stacked
structure is at most 1000 seconds.

Claims 16 to 22 (canceled).

[RESPONSE CONTINUES ON NEXT PAGE]